100% Material Declaration Data Sheet PQG240

PK124 (v1.2.1) October 19, 2006 Material Declaration Data Sheet

Average Weight: 7.1 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.08023**	**1.13%**
	Silicon	7440-21-3	100.00		0.08023	
Die Attach Material					**0.01065**	**0.15%**
	Silver	7440-22-4	78.00		0.008307	
	Epoxy (EP)	Trade Secret	22.00		0.002343	
Mold Compound					**5.72828**	**80.68%**
	Epoxy Resin (EP)	Trade Secret	9.00		0.5155452	
	Phenolic Resin	Trade Secret	7.00		0.4009796	
	Carbon Black	1333-86-4	0.50		0.0286414	
	Silica	60676-86-0	82.50		4.725831	
	Bismuth	7440-69-9	Max 1.00		0.0572828	
Leadframe					**0.79236**	**11.16%**
	Copper	7440-50-8	98.85		0.78324786	
	Chromium	7440-47-3	0.30		0.00237708	
	Tin	7440-31-5	0.25		0.0019809	
	Zinc	7440-66-6	0.60		0.00475416	
Leadframe Plating					**0.00497**	**0.07%**
	Silver	7440-22-4	100.00		0.00497	
Bond Wire					**0.0128**	**0.18%**
	Gold	7440-57-5	100.00		0.0128	
Heatspreader					**0.42813**	**6.03%**
	Alumiuim	7429-90-5	100.00		0.42813	
Ext. Plating					**0.0426**	**0.60%**
	Tin	7440-31-5	100.00		0.0426	

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
10/19/06	1.2.1	Editorial change; corrected typo in Substance Description.